

# IPC-9252A

## Requirements for Electrical Testing of Unpopulated Printed Boards

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*A standard developed by IPC*

*Association Connecting Electronics Industries*



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Developed by the Electrical Continuity Testing Task Group (7-32c)  
of the Product Assurance Committee (7-30) of IPC

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Users of this publication are encouraged to participate in the  
development of future revisions.

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